PDS BOM-TIDA-00642.xls None 11/17/2015 1:34:21 AM 00642



## **TIDA-00642 REV E1 Bill of Materials**

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB	1		TIDA-00642	Any	Printed Circuit Board	
C1, C2	2	0.1uF	08055C104KAT2A	AVX	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0805	0805
C3	1	1000pF	08051C102KAT2A	AVX	CAP, CERM, 1000 pF, 100 V, +/- 10%, X7R, 0805	0805
CE1	1	10uF	293D106X0010B2TE3	Vishay-Sprague	CAP, TA, 10 μF, 10 V, +/- 20%, 2.5 ohm, SMD	3528-21
FID1, FID2, FID3	3		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
H1	1		DRV5053OAQDBZR	Texas Instruments	IC HALL SENSOR	SOT-23
J1	1		22-23-2031	Molex	Header, 2.54 mm, 3x1, Tin, TH	Header, 2.54mm, 3x1,
						TH
R1, R2, R5, R7	4	4.7k	CRCW08054K70JNEA	Vishay-Dale	RES, 4.7 k, 5%, 0.125 W, 0805	0805
R3	1	7.5k	CRCW08057K50JNEA	Vishay-Dale	RES, 7.5 k, 5%, 0.125 W, 0805	0805
R4, R8	2	1.0k	CRCW08051K00JNEA	Vishay-Dale	RES, 1.0 k, 5%, 0.125 W, 0805	0805
R6	1	15k	CRCW080515K0JNEA	Vishay-Dale	RES, 15 k, 5%, 0.125 W, 0805	0805
RV1, RV2	2	10k	3386P-1-103LF	Bourns	TRIMMER, 10k ohm, 0.5W, TH	375x190x375mil
U1	1		LMV612MA	Texas Instruments	Dual 1.4 MHz, Low Power General Purpose, 1.8V Op Amp, D0008A	D0008A

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